Announcement

INTERNATIONAL SOCIETY FOR HYBRID MICROELECTRONICS

The International Society for Hybrid Microelectronics is based in the U.S.A., and there are independent parallel organisations throughout the world. These groups are independent, non-profitmaking organisations, the purpose of which is to provide an informal means of discussing and advancing hybrid technology. This is achieved by the organisation of meetings, the publication of a Newsletter and other activities as appropriate. Membership is open to all and there are no formal entry requirements.

All these societies run a programme of meetings throughout the year on subjects concerned with thick films, and interested readers are advised to contact the following Chairmen for details of meetings in their own areas:

1. Benelux

Mr. G. K. Steenvoorden Technische Hogeschool Delft Lorentzweg 1 NL.2628 C. J. DELFT Nederland

2. France

Dr B. Dreyfus-Alain President de I.F.M.H. 114 Rue de Danniette 91190 GIF SUR YVETTE, France

3. Germany

Herr W. Funk Philips Forschungslaboratorium GmbH 2 HAMBURG 54 Postfach 540840 Deutschland

4. Italy

Dr D. Roggia Telettra Via Trento 30 20059 VIMERCATE Italy

5. Japan

Dr A. Ikegami Hitachi Ltd. 292 Yoshida-Cho Totsuka-ku YOKOHAMA Japan

6. Nordic

Mr E. Järvinen Lohja Corporation Electronics Division Box 47 SF-08101 Lohja 10 Finland

7. U.K.

Mr. A. Fairbairn Semi-Alloys Inc. Newbury, Berkshire, U.K.

8. U.S.A. – all U.S. Chapters I.S.H.M. P.O. Box 3255 MONTGOMERY Alabama 36109, U.S.A.

In addition, the European Chapters are all linked together through the European Liaison Committee. Chairman:

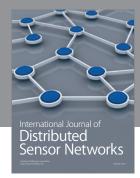
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